

BB02-CN :- 1.27mm x 1.27mm (0.05" x 0.05") SOCKET, THROUGH HOLE, DUAL ROW, STRAIGHT - 06 to 100 CONTACTS

SPECIFICATIONS

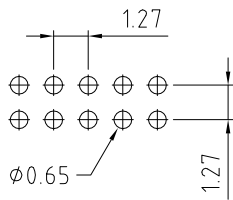
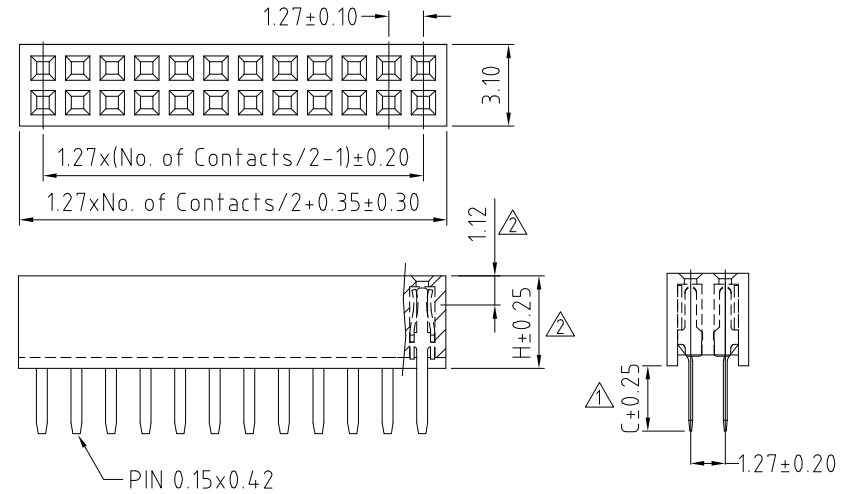
CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	300 V AC/DC
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOLPASTIC, UL 94V-0
	STANDARD: LCP
PLATING	GOLD, TIN, OR SELECTIVE OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC
	WAVE: 250°C FOR 5-10 SEC
	MANUAL SOLDER: 380°C FOR 3-5 SEC

NOTES:
1. RECOMMENDED MATING PIN LENGTH: 3.0MM Δ

MATES WITH :-

BB02-BC	BB02-BS	BB02-7B
BB02-BD	BB02-BY	
BB02-BE	BB02-BZ	
BB02-BK	BB02-NE	
BB02-BP	BB02-NN	

NOTE: BE, BY, BZ, NN AND 7B WILL ACCEPT 4.40MM HIGH SOCKET.



RECOMMENDED PC BOARD HOLE LAYOUT
(TOLERANCE: ±0.05)

HOW TO ORDER



NO. OF CONTACTS:
06 TO 98
00 = 100

'H' HEIGHT OPTIONS:
A = 3.4MM (C=2.17)
B = 4.4MM (C=2.3)

PACKAGING OPTIONS: Δ
3 = TUBE (STANDARD)
8 = TAPE & REEL + CAP

Δ CONTACT PLATING OPTIONS:

- K = GOLD FLASH (STANDARD)
- A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- T = BRIGHT TIN
- M = MATT TIN
- D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL

REV.	DATE & DRN
10	06/04/05 - NYW RELEASE
11	17/01/06 - NYW
12	22/02/06 - NYW
13	20/07/06 - NYW
14	02/05/07 - NYW
15	30/04/08 - NYW
16	26/07/08 - CHC
17	03/07/09 - NYW
18	15/04/10 - NYW
19	11/08/10 - NYW

10	06/04/05 - NYW RELEASE
11	17/01/06 - NYW
12	22/02/06 - NYW
13	20/07/06 - NYW
14	02/05/07 - NYW
15	30/04/08 - NYW
16	26/07/08 - CHC
17	03/07/09 - NYW
18	15/04/10 - NYW
19	11/08/10 - NYW

Scale:	5:1
Drawn:	CHC
App'd:	XXXX
Date:	23 OCT. '14

THIRD ANGLE	
Title	SOCKET
Revision:	1.9

Unstated Tolerances:	X ± 0.30
	X ± 0.25
	.XX ± 0.15
	.XXX ± 0.10

Material	SEE NOTE
UNIT:	mm

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